
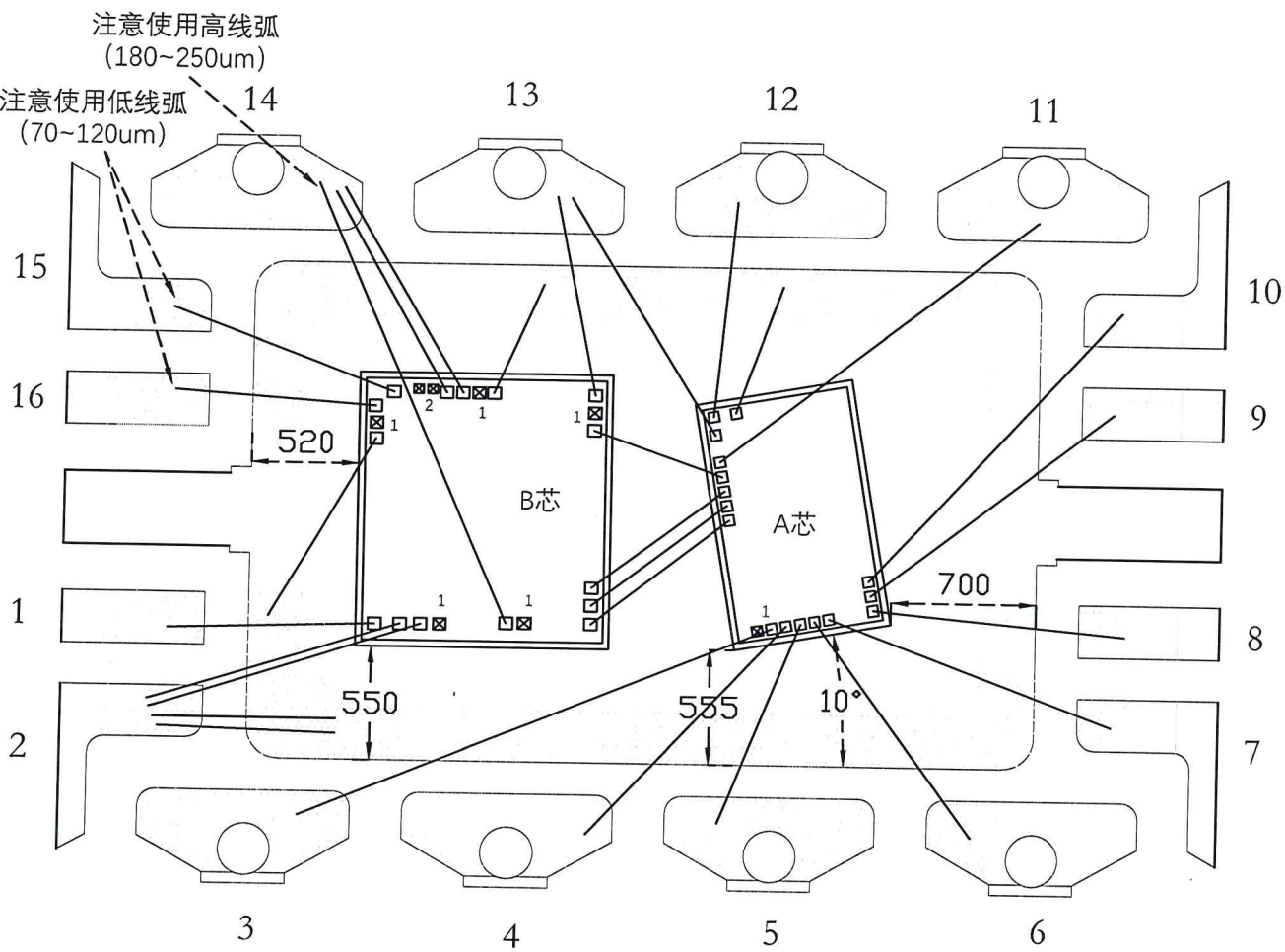
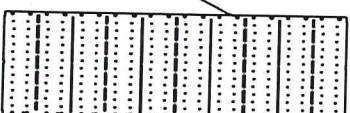


<div>池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD</div>				客户代码 Customer No.		008		线图号 Drawing No.		HY-PX-008-754 A					
焊线图纸 Bonding Diagram				产品名称 Product Type		WL2612		封装外型 PKG Type		SOP16L(12R)					
焊线种类 Wire Type		焊线直径(μm) Wire Diameter		焊线根数 NO. of wire		焊线总长(μm) Total wire length		最长线长(μm) Longest wire length		最短线长(μm) Shortest wire length		塑封料型号(绿色环保) Compound Type (Green)		LF载体尺寸 LF Pad Size	
合金丝 Ag		20		29		41442		2555		570		首选(Preferred): CEL-1702HF 备选(Optional): EME-G630AY		SOP16L-12R (94*150mil) (2390*3810um ²)	
客户图号 Customer drawing NO.															

注意使用高线弧
(180~250um)

注意使用低线弧
(70~120um)



框架传送方向(裁片): L/F Direction (D/A):				实物图: Chip photo:				特殊说明 Special Instructions:							
<div>椭圆孔</div> 								<div>DB注意:</div> <div>1.以随工单要求按顺序装片,如:先装A芯片,装B芯片时必须装在有A芯片的框架,反之先装B芯片,装A芯片时B芯已经装片;</div> <div>2.控制溢胶,为WB预留焊线位置;</div> <div>WB注意:</div> <div>1.数字为不打线pad个数;</div> <div>2.植球点在B芯</div>							

说明 Instructions	粘片胶类型 Epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPO (μm ²)	最小焊盘间距 Min BPP(μm)	铝垫厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Street line (μm)	晶圆尺寸 Wafer Size	是否是 Low-K If low-k?	减薄厚度 (μm) Wafer Thickness
A芯: DIE A	导电胶 (conductivity) S210	HS5159	1135*709(μm ²) 44.69*27.91(mil ²)	50*50	70	0.8	是/Yes	60	8	否/NO	200
B芯: DIE B	导电胶 (conductivity) S210	WL1710	1165*1259(μm ²) 45.67*49.57(mil ²)	62.05*56.1	70	3.4	是/Yes	60	8	否/NO	200
C芯: DIE C											

拟制 Prepared by	制图日期 Create Date	生效日期 Effective Date	客户确认签字/盖章: Customer Signature
研发审核 R&D Check	产品工程审核 PE Check	批准 Approved by	

*温馨提示: 图纸为产品下线生产的唯一依据, 请您认真确认, 我司依据您回签后的图纸生产, 如因图纸错误会产生不可估量损失, 谢谢!

*warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce incalculable loss. Thank you

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